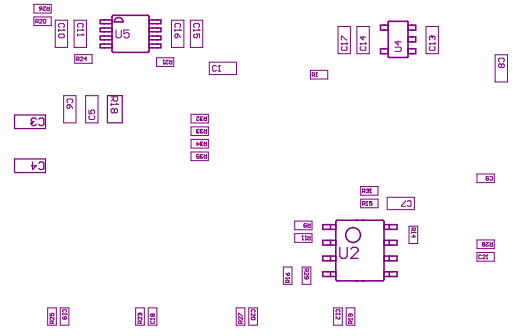


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01445	REV: E1	SVN REV: Not In VersionControl
	TID #: N/A		
PLOT NAME = Top Assembly Drawing	GENERATED : 8/25/2017 1:43:30 PM		TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01445	REV: E1	SUN REV: Not In VersionControl
	TID #: N/A		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 8/25/2017 1:43:34 PM		TEXAS INSTRUMENTS

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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